



# PHOTOCOUPLER PS2913-1

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## SINGLE Tr. OUTPUT, HIGH COLLECTOR TO EMITTER VOLTAGE 4-PIN ULTRA SMALL FLAT-LEAD PHOTOCOUPLER

–NEPOC Series–

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### DESCRIPTION

The PS2913-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor in one package for high density mounting applications.

An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 30% compared with the PS28xx series.

### FEATURES

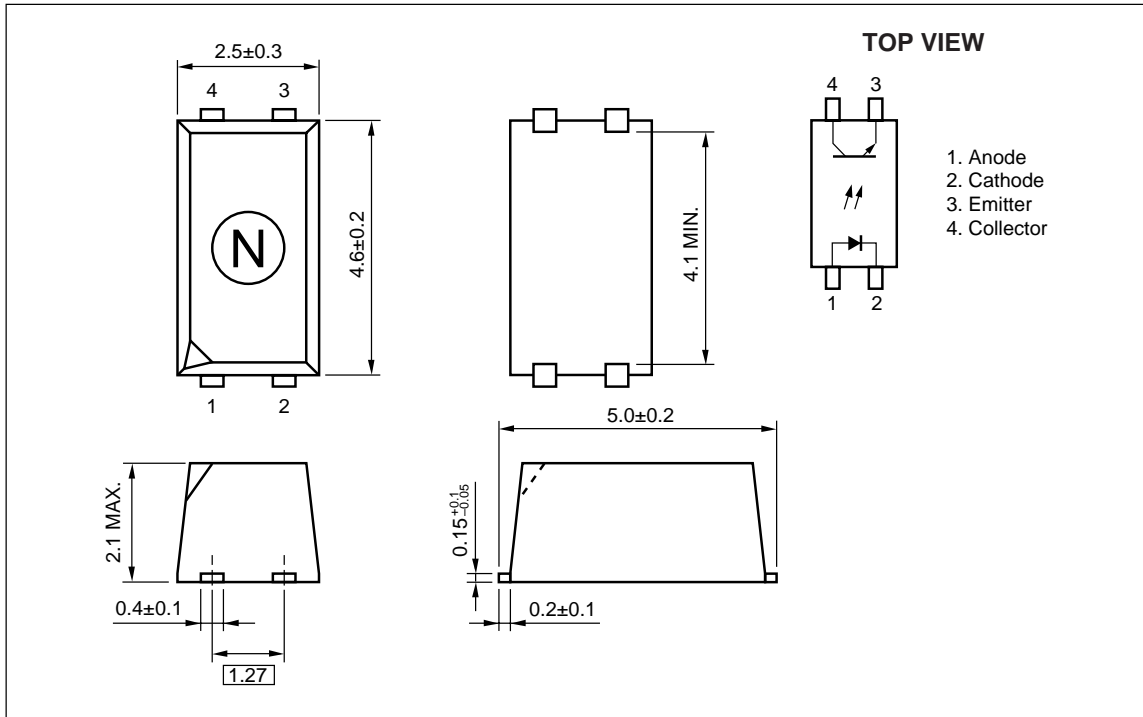
- Ultra small flat-lead package (4.6 (L) × 2.5 (W) × 2.1 (H) mm)
- Isolation distance (0.4 mm MIN.)
- High collector to emitter voltage ( $V_{CEO} = 120$  V)
- High isolation voltage ( $BV = 2\ 500$  Vr.m.s.)
- Ordering number of taping product: PS2913-1-F3, F4: 3 500 pcs/reel
- <R> • Safety standards
  - UL approved: File No. E72422
  - BSI approved: No. 8657, 8658
  - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

### APPLICATIONS

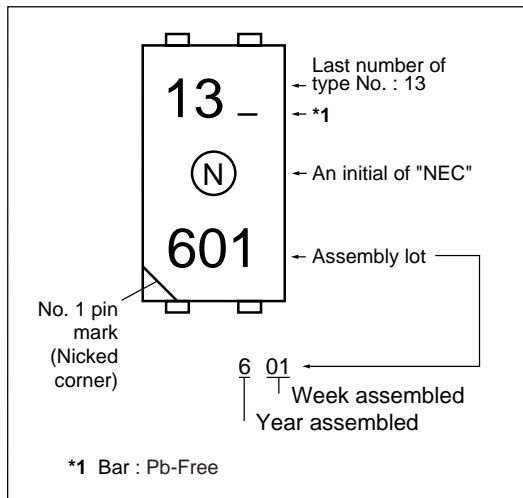
- Hybrid IC
- Power supply

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**PACKAGE DIMENSIONS (UNIT: mm)**



<R> **MARKING EXAMPLE**



**PHOTOCOUPLER CONSTRUCTION**

Parameter	Unit (MIN.)
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.4 mm

## &lt;R&gt; ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS2913-1	PS2913-1-A	Pb-Free	50 pcs (Tape 50 pcs cut)	Standard products (UL, BSI approved)	PS2913-1
PS2913-1-F3	PS2913-1-F3-A		Embossed Tape 3 500 pcs/reel		
PS2913-1-F4	PS2913-1-F4-A				
PS2913-1-V	PS2913-1-V-A		50 pcs (Tape 50 pcs cut)	DIN EN60747-5-2 (VDE0884 Part2) Approved (Option)	
PS2913-1-V-F3	PS2913-1-V-F3-A		Embossed Tape 3 500 pcs/reel		
PS2913-1-V-F4	PS2913-1-V-F4-A				

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I <sub>F</sub>	50	mA
	Forward Current Derating	ΔI <sub>F</sub> /°C	0.5	mA/°C
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	0.5	A
	Power Dissipation	P <sub>D</sub>	60	mW
	Reverse Voltage	V <sub>R</sub>	6	V
Transistor	Collector to Emitter Voltage	V <sub>CEO</sub>	120	V
	Emitter to Collector Voltage	V <sub>ECC</sub>	6	V
	Collector Current	I <sub>C</sub>	30	mA
	Power Dissipation Derating	ΔP <sub>C</sub> /°C	1.2	mW/°C
	Power Dissipation	P <sub>C</sub>	120	mW
Isolation Voltage <sup>*2</sup>		BV	2 500	Vr.m.s.
Total Power Dissipation		P <sub>T</sub>	160	mW
Operating Ambient Temperature		T <sub>A</sub>	-55 to +100	°C
Storage Temperature		T <sub>stg</sub>	-55 to +150	°C

\*1 PW = 100 μs, Duty Cycle = 1%

\*2 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output  
Pins 1-2 shorted together, 3-4 shorted together.

ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 1 mA	0.9	1.1	1.3	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5	μA
	Terminal Capacitance	C <sub>t</sub>	V = 0 V, f = 1 MHz		15		pF
Transistor	Collector to Emitter Dark Current	I <sub>CEO</sub>	I <sub>F</sub> = 0 mA, V <sub>CE</sub> = 120 V			100	nA
Coupled	Current Transfer Ratio (I <sub>c</sub> /I <sub>F</sub> ) <sup>*1</sup>	CTR	I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V	50	100	200	%
	Collector Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> = 1 mA, I <sub>c</sub> = 0.2 mA		0.13	0.3	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kV <sub>DC</sub>	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time <sup>*2</sup>	t <sub>r</sub>	V <sub>CC</sub> = 5 V, I <sub>c</sub> = 2 mA, R <sub>L</sub> = 100 Ω		10		μs
	Fall Time <sup>*2</sup>	t <sub>f</sub>			10		μs
	On Time <sup>*2</sup>	t <sub>on</sub>	V <sub>CC</sub> = 5 V, I <sub>F</sub> = 1 mA, R <sub>L</sub> = 5 kΩ		80		μs
	Storage Time <sup>*2</sup>	t <sub>s</sub>			5		μs
Off Time <sup>*2</sup>	t <sub>off</sub>			50		μs	

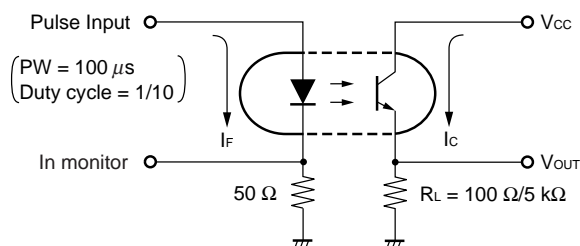
**\*1** CTR rank

N : 50 to 200 (%)

K : 100 to 200 (%)

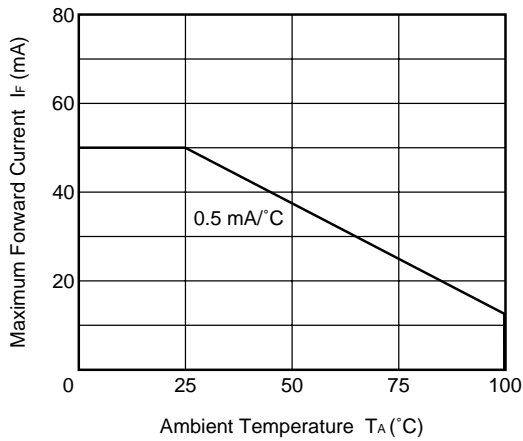
L : 75 to 150 (%)

M : 50 to 100 (%)

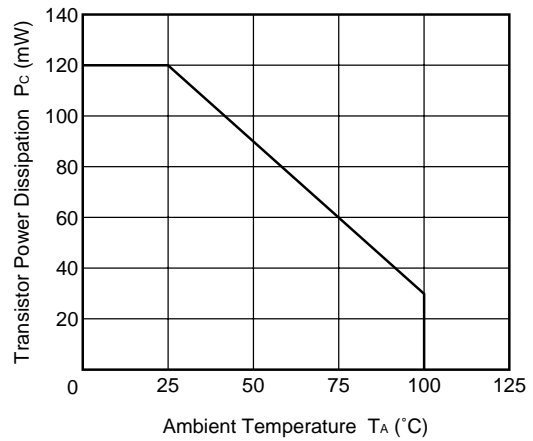
**\*2** Test circuit for switching time

**TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**

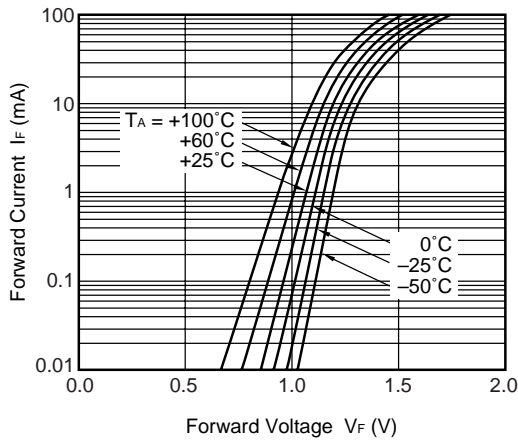
**MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE**



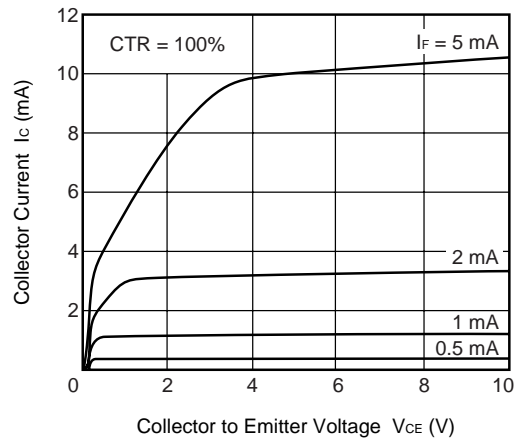
**TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE**



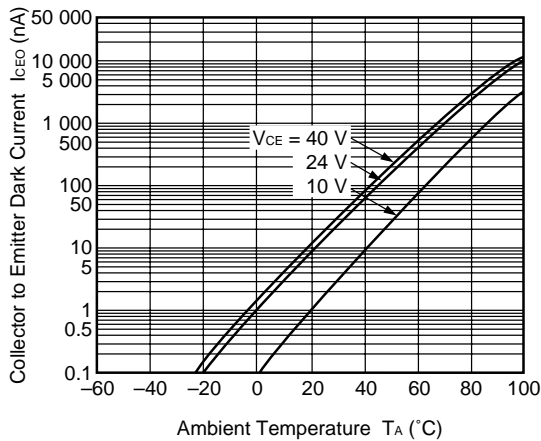
**FORWARD CURRENT vs. FORWARD VOLTAGE**



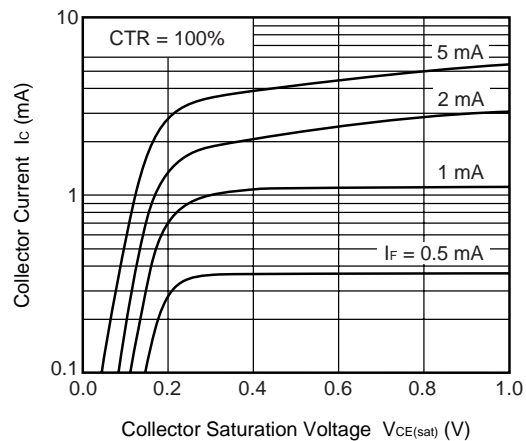
**COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE**



**COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE**

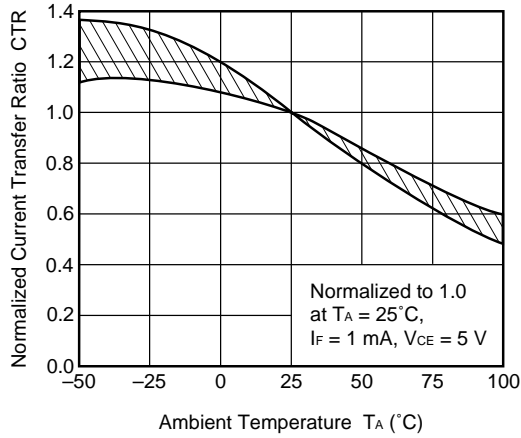


**COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE**

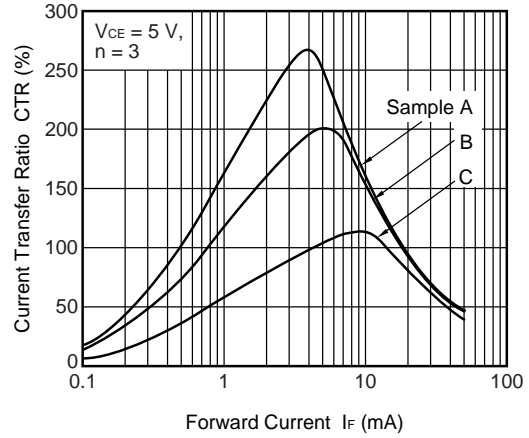


**Remark** The graphs indicate nominal characteristics.

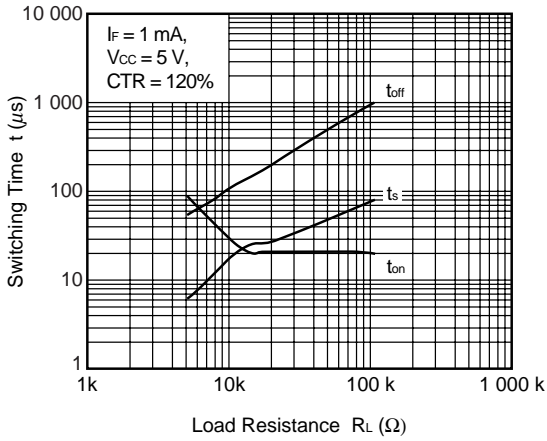
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



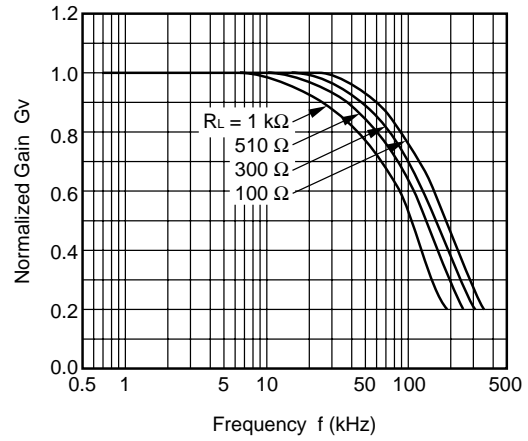
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



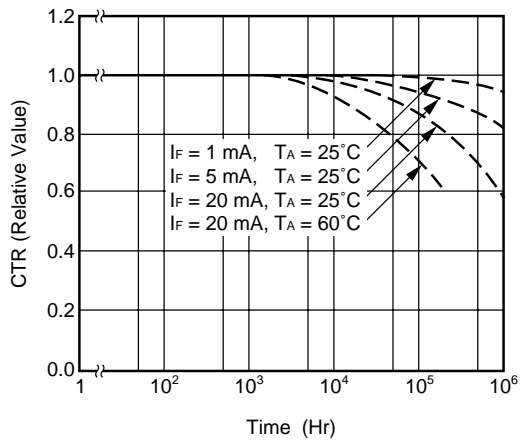
SWITCHING TIME vs. LOAD RESISTANCE



FREQUENCY RESPONSE



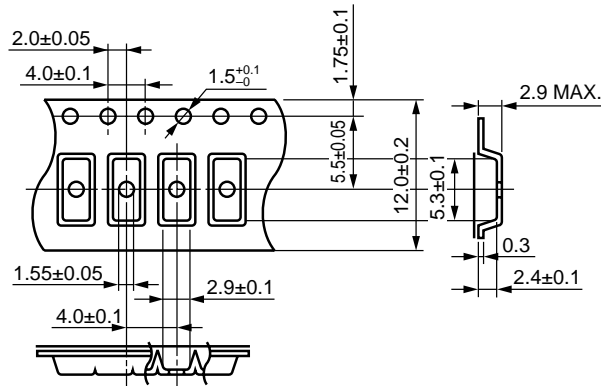
LONG TERM CTR DEGRADATION



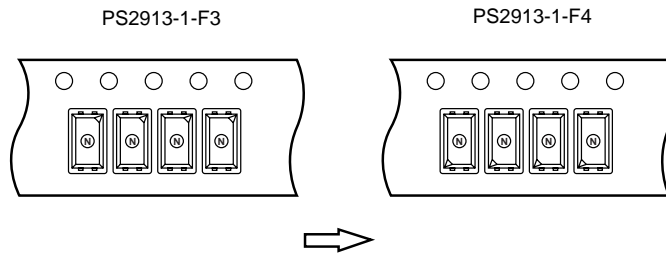
**Remark** The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

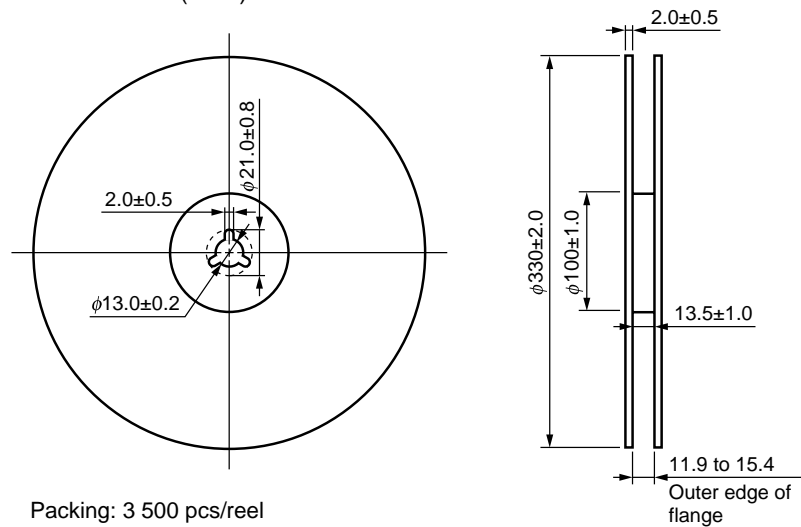
Outline and Dimensions (Tape)



Tape Direction

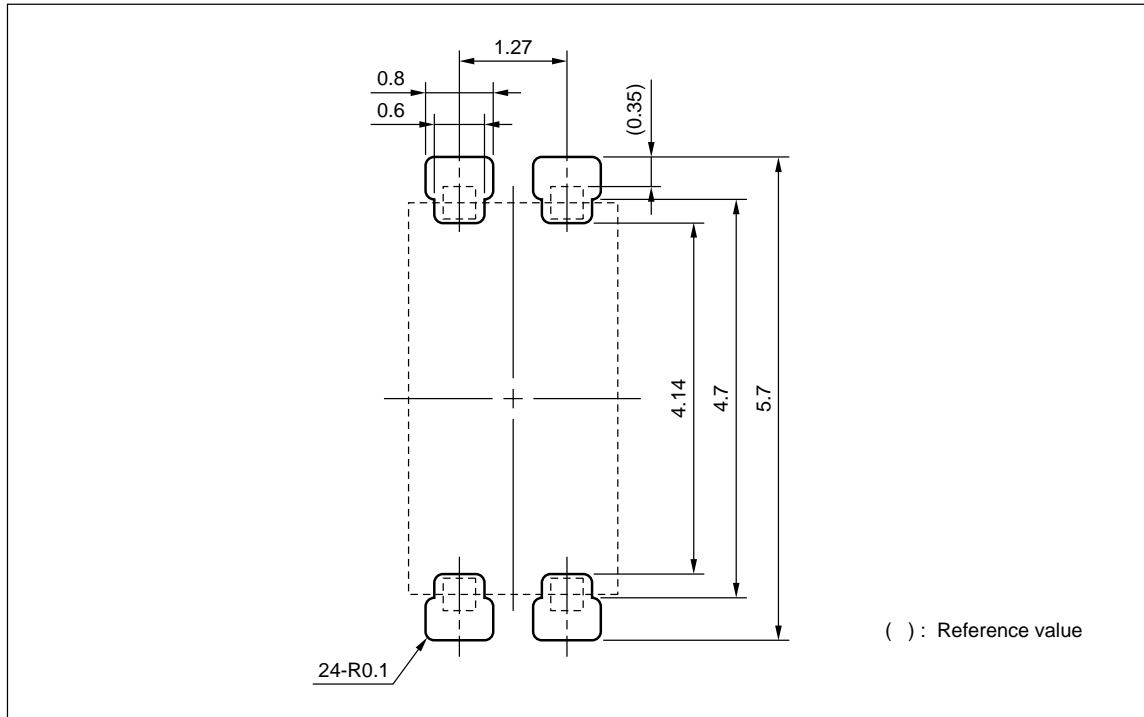


Outline and Dimensions (Reel)



Packing: 3 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



**Remark** This drawing is considered to meet air and outer creepage distance 4.0 mm minimum. All dimensions in this figure must be evaluated before use.



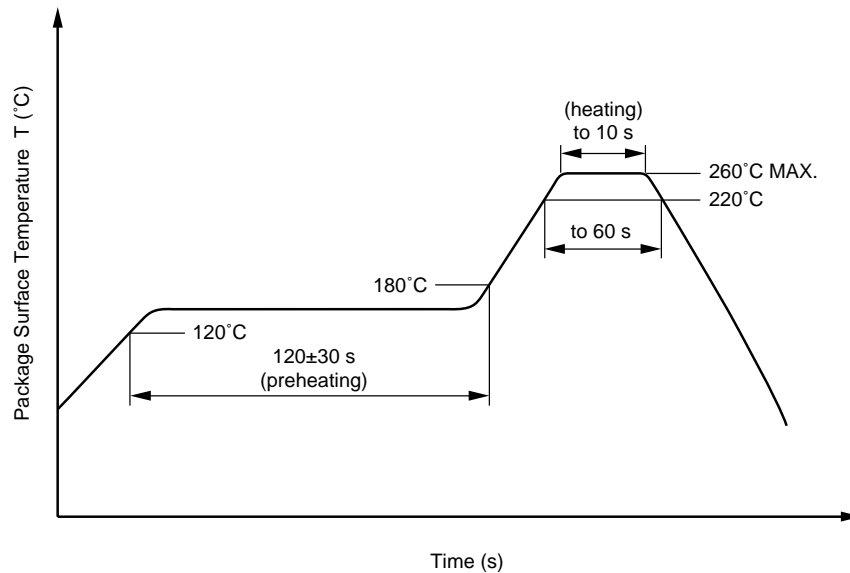
## NOTES ON HANDLING

## 1. Recommended soldering conditions

## (1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



## (2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

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## (3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

**(4) Cautions**

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

**2. Cautions regarding noise**

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

**<R> 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler**

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

**USAGE CAUTIONS**

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

<p><b>Caution</b></p>	<p>GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> <li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.             <ol style="list-style-type: none"> <li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> <li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li> </ol> </li> <li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li> <li>• Do not lick the product or in any way allow it to enter the mouth.</li> </ul>
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► For further information, please contact

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